MOSFETs Silicon N-channel MOS (U-MOSIX-H)

# TPH1R204PL1

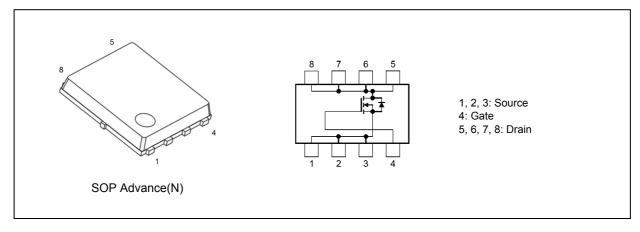
#### 1. Applications

- High-Efficiency DC-DC Converters
- Switching Voltage Regulators

#### 2. Features

- (1) High-speed switching
- (2) Small gate charge:  $Q_{SW} = 17 \text{ nC}$  (typ.)
- (3) Small output charge:  $Q_{oss} = 56 \text{ nC}$  (typ.)
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 1.0 \text{ m}\Omega$  (typ.) (V<sub>GS</sub> = 10 V)
- (5) Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 40 \ V)$
- (6) Enhancement mode:  $V_{th}$  = 1.4 to 2.4 V ( $V_{DS}$  = 10 V,  $I_D$  = 0.5 mA)

#### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25 \,^{\circ}C$ unless otherwise specified)

Characterist	ics		Symbol	Rating	Unit
Drain-source voltage			V <sub>DSS</sub>	40	V
Gate-source voltage			V <sub>GSS</sub>	±20	
Drain current (DC)	(T <sub>c</sub> = 25 °C)	(Note 1), (Note 2)	Ι <sub>D</sub>	150	A
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	Ι <sub>D</sub>	270	A
Drain current (pulsed)	(t = 100 μs)	(Note 1)	I <sub>DP</sub>	500	A
Power dissipation	(T <sub>c</sub> = 25 °C)		PD	170	W
Power dissipation		(Note 3)	PD	3	w
Power dissipation		(Note 4)	PD	0.96	w
Single-pulse avalanche energy		(Note 5)	E <sub>AS</sub>	125	mJ
Single-pulse avalanche current		(Note 5)	I <sub>AS</sub>	120	A
Channel temperature			T <sub>ch</sub>	175	°C
Storage temperature			T <sub>stg</sub>	-55 to 175	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

Characteristics			Symbol	Max	Unit
Channel-to-case thermal resistance	(T <sub>c</sub> = 25 °C)		R <sub>th(ch-c)</sub>	0.88	°C/W
Channel-to-ambient thermal resistance	(T <sub>a</sub> = 25 °C)	(Note 3)	R <sub>th(ch-a)</sub>	50	
Channel-to-ambient thermal resistance	(T <sub>a</sub> = 25 °C)	(Note 4)	R <sub>th(ch-a)</sub>	156	

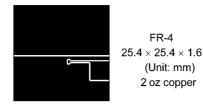
Note 1: Ensure that the channel temperature does not exceed 175 °C.

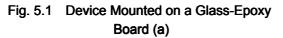
Note 2: Limited by package limit. Silicon chip capability is 270 A. ( $T_c = 25 \text{ °C}$ )

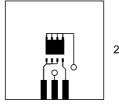
Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5: V\_{DD} = 32 V, T\_{ch} = 25 °C (initial), L = 0.0067 mH, I\_{AS} = 120 A







FR-4 25.4 × 25.4 × 1.6 (Unit: mm) 2 oz copper

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

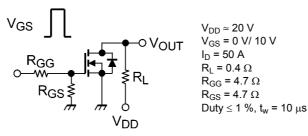
#### 6. Electrical Characteristics

#### 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20 V, $V_{DS}$ = 0 V		_	±0.1	μA
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V		_	10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	40	_	_	V
	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	25	_	_	
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.5 mA	1.4	_	2.4	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 50 A		1.5	2.1	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 50 A		1.0	1.24	

#### 6.2. Dynamic Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz		5500	7200	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	93	_	
Output capacitance	C <sub>oss</sub>			1300	_	
Gate resistance	r <sub>g</sub>	—		0.6	1.1	Ω
Switching time (rise time)	tr	See Fig. 6.2.1	_	13	_	ns
Switching time (turn-on time)	t <sub>on</sub>	]		33	_	
Switching time (fall time)	t <sub>f</sub>	]		10	_	
Switching time (turn-off time)	t <sub>off</sub>	]		58	_	



#### Fig. 6.2.1 Switching Time Test Circuit

#### 6.3. Gate Charge Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Qg	$V_{DD}\approx 20~V,~V_{GS} \text{ = } 10~V,~I_{D} \text{ = } 50~\text{A}$	_	74	_	nC
gate-drain)		$V_{DD}\approx 20~V,~V_{GS}$ = 4.5 V, $I_{D}$ = 50 A	—	34	_	
Gate-source charge 1	Q <sub>gs1</sub>	$V_{DD} \approx 20$ V, $V_{GS}$ = 10 V, $I_D$ = 50 A	_	16	_	
Gate-drain charge	Q <sub>gd</sub>		_	17	_	
Gate switch charge	Q <sub>SW</sub>		_	17	_	
Output charge	Q <sub>oss</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V	_	56	_	

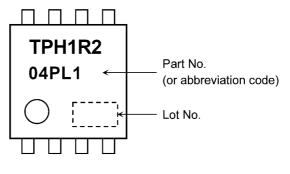
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### 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25 $^{\circ}$ C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note 6)	I <sub>DRP</sub> (t = 100 μs)	_	—	—	500	A
Diode forward voltage	V <sub>DSF</sub>	I <sub>DR</sub> = 150 A, V <sub>GS</sub> = 0 V	_	—	-1.2	V
Reverse recovery time	t <sub>rr</sub>	V <sub>R</sub> = 20 V, I <sub>DR</sub> = 37.5 A, V <sub>GS</sub> = 0 V, -dI <sub>DR</sub> /dt = 100 A/μs	_	46	—	ns
Reverse recovery charge	Q <sub>rr</sub>	V <sub>R</sub> = 20 V, I <sub>DR</sub> = 37.5 A, V <sub>GS</sub> = 0 V, -dI <sub>DR</sub> /dt = 100 A/μs		46		nC

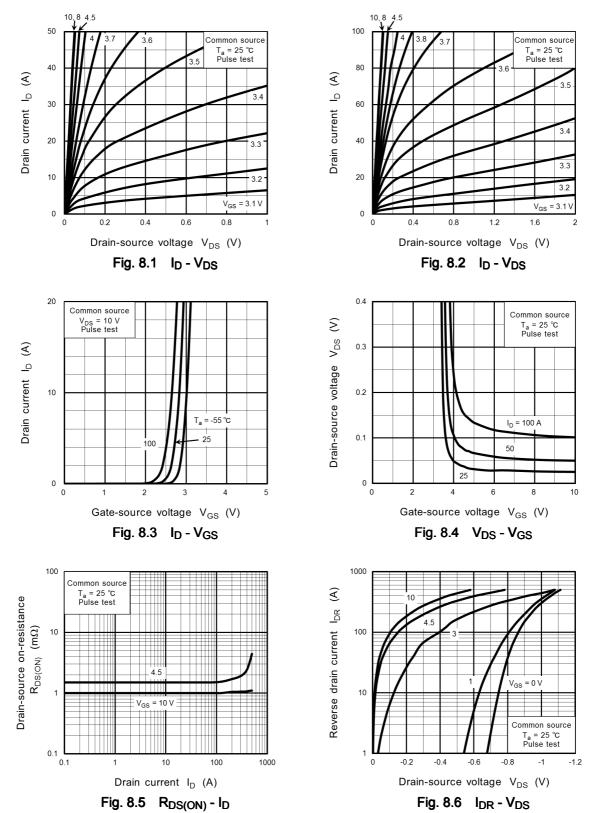
Note 6: Ensure that the channel temperature does not exceed 175 °C.

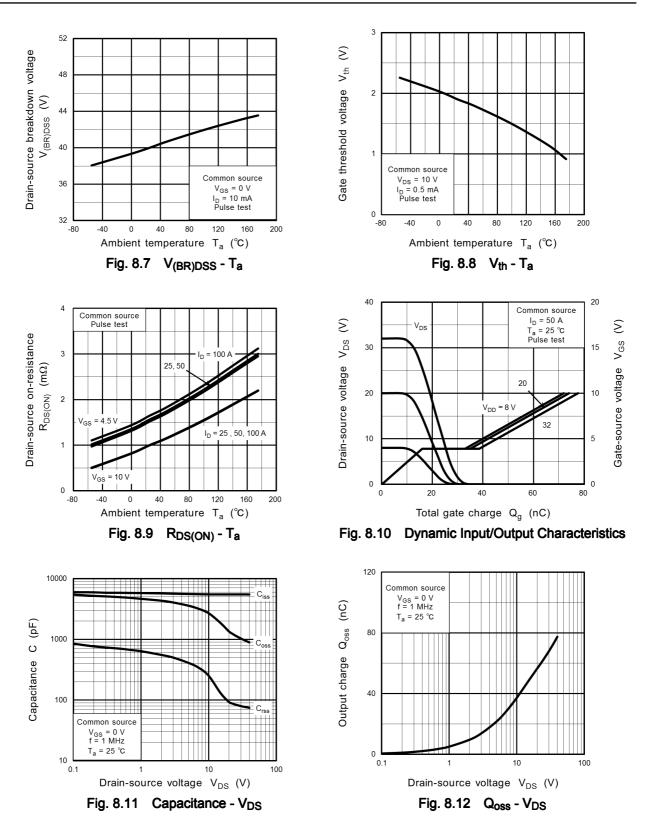
#### 7. Marking

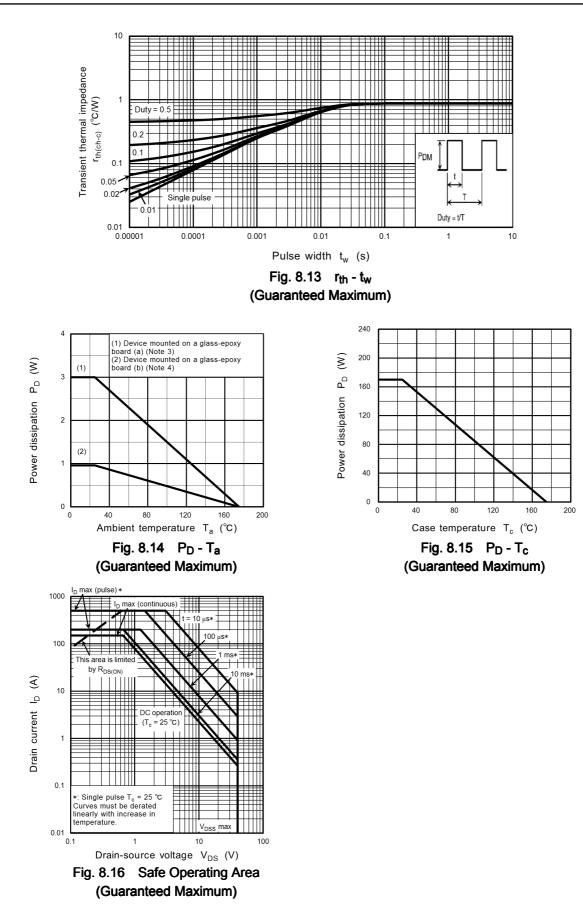




#### 8. Characteristics Curves (Note)







Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

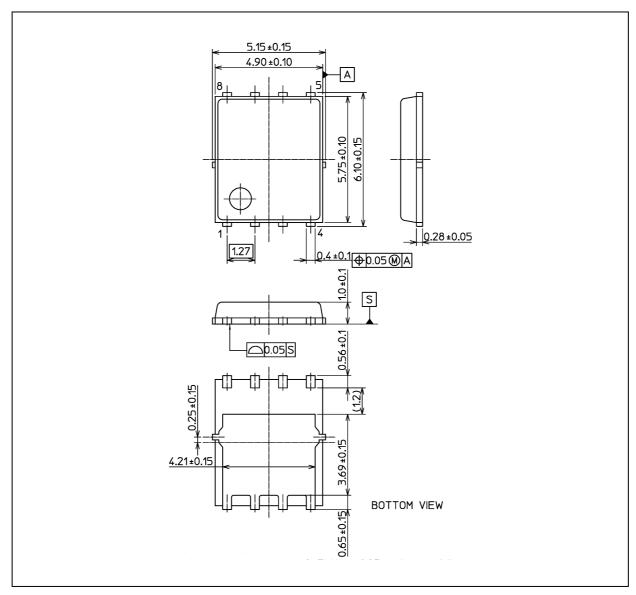
TOSHIBA



### TPH1R204PL1

#### **Package Dimensions**

Unit: mm



Weight:	0.105	g (typ.)
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Package Name(s)
TOSHIBA: 2-5W1A
Nickname: SOP Advance(N)

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